

CSSOP

Ceramic Shrink Small Outline Package (CSSOP)

This is a ceramic version of the Plastic SSOP package. The CSSOP is a hermetic package consisting of two pieces of dry pressed ceramic surrounding a "gullwing" formed leadframe. This package has leads extending from two sides of the package (dual). The ceramic / LF / ceramic system is held together hermetically by glass. The frit lid is sealed/reflowed over the package cavity at temperatures between 400° - 460° Centigrade.

Applications:

These packages enable end products (pagers, portable audio / video, disc drives, radio, RF devices / components, telecom) to be reduced in size and weight. Semiconductor families such as operational amplifiers, drivers, optoelectronics, controllers, logic, analog, memory, comparators and more using BiCMOS, CMOS or other silicon/GaAs technologies are well addressed by Amkor's CSSOP product family.

Features:

The CSSOP offers a variety of features:

- 20 & 24 lead counts (Others available when tooled)
- 150 mil body size (Others available when tooled)
- Hermetic package
- High thermal conductive ceramic
- Matte Tin Plate lead finish
- JEDEC and EIAJ package outline standard compliant
- Wide selection of cavity sizes to meet most die size needs
- Commercial or full Military flows